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COPY

1. Name of conveying party(ies):

(a) ILL HEUNG CHOI

6-10-04

Additional name(s) of conveying party(ies) attached?

☐ Yes☒ No

2. Name and address of receiving party(ies):

Name: Samsung Electronics Co., Ltd.

Street Address: 416, Maetan-dong, Paldal-Ku

City: Suwon-city, Kyungki-do

Country: Republic of Korea

17302 U.S. PTO
10/864508

061004

3. Nature of Conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other

Execution Date: 15 May 2002

Name and address of receiving party(ies):

Name:

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☐ Yes☒ No

4. Application number(s) or patent number(s):

10864508

If this document is being filed together with a new application, the execution date of the application is: 15 May 2002

A. Patent Application No.(s) -

Title: Semiconductor Package With Semiconductor Chips
Stacked Therein And Method Of Making The Package

B. Patent No.(s)

Additional numbers attached?



Yes



No

5. Name and address of party to whom correspondence
concerning document should be mailed:

Name: David W. Heid

Internal Address: SKJERVEN MORRILL LLP

Street Address: 25 METRO DRIVE, SUITE 700

City SAN JOSE State CA Zip 95110

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$40.00



Authorized to be charged to Deposit Account 19-2386

Charge Deposit Account 19-2386 for any additional fees
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8. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the
original document.

David W. Heid

25.875

Name of Person Signing

Signature

May 28, 2002

Date

Total number of pages including cover sheet, attachments, and documents: 1

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PATENT
REEL: 015458 FRAME: 0223

ASSIGNMENT

For good and valuable consideration, receipt of which is hereby acknowledged, I, **ILL HEUNG CHOI** of the Republic of Korea, hereby sell, assign and transfer to **Samsung Electronics Co., LTD.**, a Korean corporation, having a place of business at 416, Maetan-dong, Paldal-ku, Suwon-city Kyungki-do, Republic of Korea, its successors and assigns, the entire right, title and interest throughout the world in my invention in

**SEMICONDUCTOR PACKAGE WITH SEMICONDUCTOR CHIPS STACKED
THEREIN AND METHOD OF MAKING THE PACKAGE**

for which I have executed a United States patent application on or about the date of this assignment, and all patent applications and patents of every country for said invention, including divisions, reissues, continuations and extensions thereof, and all rights of priority resulting from the filing of said applications; I authorize the above-named assignee to apply for patents of foreign countries for said invention, and to claim all rights of priority without further authorization from me; I agree to execute all papers useful in connection with said United States and foreign applications, and generally to do everything possible to aid said assignee, its successors, assigns and nominees, at their request and expense, in obtaining and enforcing patents for said invention in all countries; and I request that the United States Patent and Trademark Office issue all patents granted for said invention to the above-named assignee, its successors and assigns.

Executed this ____ day of 15. MAY, 2002.

ILL. HEUNG. CHOI
ILL HEUNG CHOI